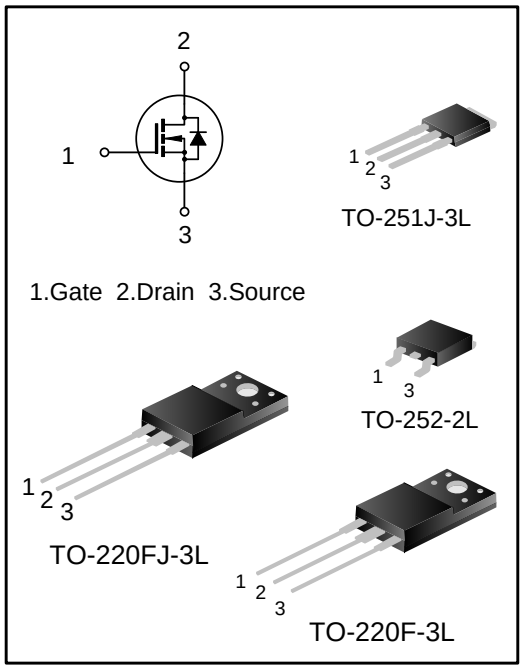
7A, 650V SUPER JUNCTION MOS POWER TRANSISTOR

DESCRIPTION

SVS7N65D(F)(MJ)(FJ)D2 is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's super junction MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, for example, it is suitable for hard and soft switching topologies, Lighting, Adapters, etc.



FEATURES

- 7A,650V, $R_{DS(on)(typ.)}$=0.55Ω@V_{GS}=10V
- New revolutionary high voltage technology
- Ultra low gate charge
- Enhanced avalanche capability
- Extreme dv/dt rated
- High peak current capability

ORDERING INFORMATION

Part No.	Package	Marking	Hazardous substance control	Packing Type
SVS7N65DD2TR	TO-252-2L	SVS7N65DD2	Halogen free	Tape & Reel
SVS7N65FD2	TO-220F-3L	SVS7N65FD2	Halogen free	Tube
SVS7N65MJD2	TO-251J-3L	7N65MJD2	Halogen free	Tube
SVS7N65FJD2	TO-220FJ-3L	7N65FJD2	Halogen free	Tube

ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, T_A=25°C)

Characteristics		Symbol	Ratings		Unit
			SVS7N65DD2/MJD2	SVS7N65FD2/FJD2	
Drain-Source Voltage		V_{DS}	650		V
Gate-Source Voltage		V_{GS}	±30		V
Drain Current	T_C=25°C	I_D	7.0		A
	T_C=100°C		4.4		
Drain Current Pulsed		I_{DM}	28		A
Power Dissipation (T_C=25°C)		P_D	60	30	W
- Derate above 25°C			0.48	0.24	W/°C
Single Pulsed Avalanche Energy (Note 1)		E_{AS}	261		mJ
Reverse diode dv/dt (Note 2)		dv/dt	15		V/ns
MOSFET dv/dt ruggedness (Note 3)		dv/dt	50		V/ns
Operation Junction Temperature Range		T_J	-55～+150		°C
Storage Temperature Range		T_{stg}	-55～+150		°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVS7N65DD2/MJD2	SVS7N65FD2/FJD2	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.08	4.17	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.0	62.5	°C/W

ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED, T_C=25°C)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V, I_D=250μA	650	--	--	V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=650V, V_{GS}=0V	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS}=±30V, V_{DS}=0V	--	--	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS}=V_{DS}, I_D=250μA	2.0	--	4.0	V
Static Drain- Source on State Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=3.5A	--	0.55	0.64	Ω
Gate resistance	R_g	f=1MHz	--	7.0	--	Ω
Input Capacitance	C_{iss}	V_{DS}=100V, V_{GS}=0V, f=1.0MH$_Z$	--	423	--	pF
Output Capacitance	C_{oss}		--	27	--	
Reverse Transfer Capacitance	C_{rss}		--	1.9	--	
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=325V, I_D=7.0A, V_{GS}=10V, R_G=24Ω (Note 4,5)	--	10	--	ns
Turn-on Rise Time	t_r		--	29	--	
Turn-off Delay Time	$t_{d(off)}$		--	44	--	
Turn-off Fall Time	t_f		--	26	--	
Total Gate Charge	Q_g	V_{DS}=520V, I_D=7.0A, V_{GS}=10V (Note 4,5)	--	16	--	nC
Gate-Source Charge	Q_{gs}		--	3.6	--	
Gate-Drain Charge	Q_{gd}		--	8.3	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	7.0	A
Pulsed Source Current	I_{SM}		--	--	28	
Diode Forward Voltage	V_{SD}	I_S=7.0A,V_{GS}=0V	--	--	1.4	V
Reverse Recovery Time	T_{rr}	I_S=7.0A,V_{GS}=0V, dI_F/dt=100A/μs (Note 4)	--	346	--	ns
Reverse Recovery Charge	Q_{rr}		--	2.5	--	μC

Notes:

1. L=79mH,I_{AS}=2.4A,V_{DD}=100V, R_G=25Ω, starting temperature T_J=25°C;
2. V_{DS}=0~400V,I_{SD}<=7.0A, T_J=25°C;
3. V_{DS}=0~480V;
4. Pulse Test: Pulse width ≤300μs,Duty cycle≤2%;
5. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

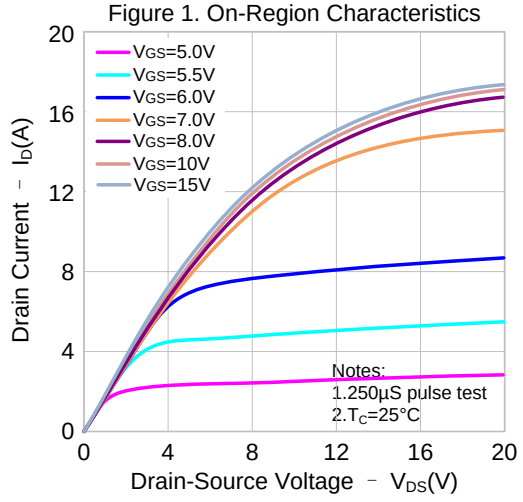


Figure 2. Transfer Characteristics

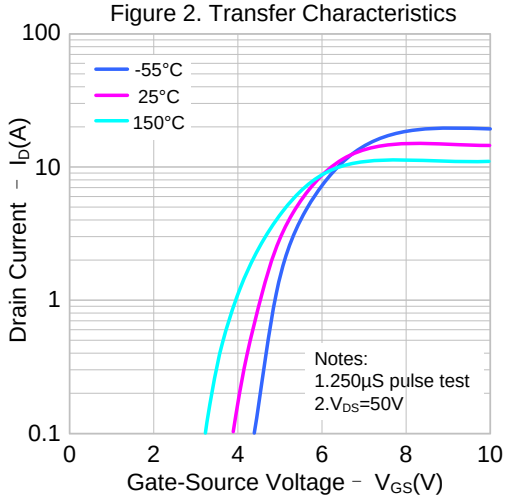


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

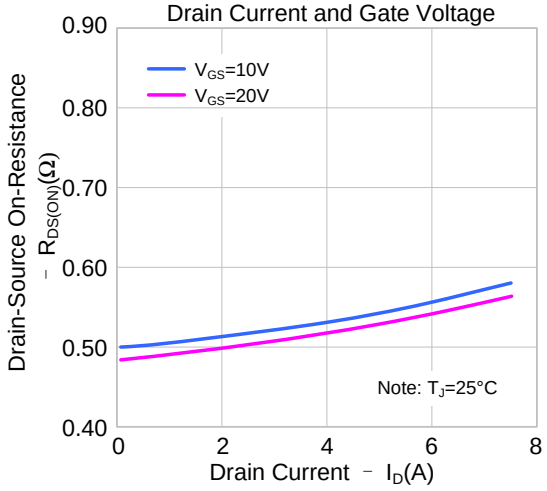


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

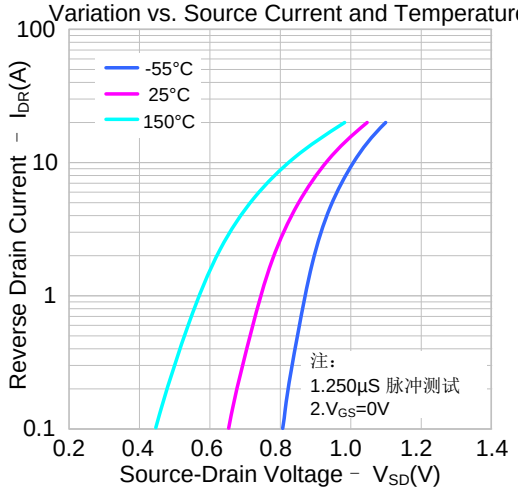


Figure 5. Capacitance Characteristics

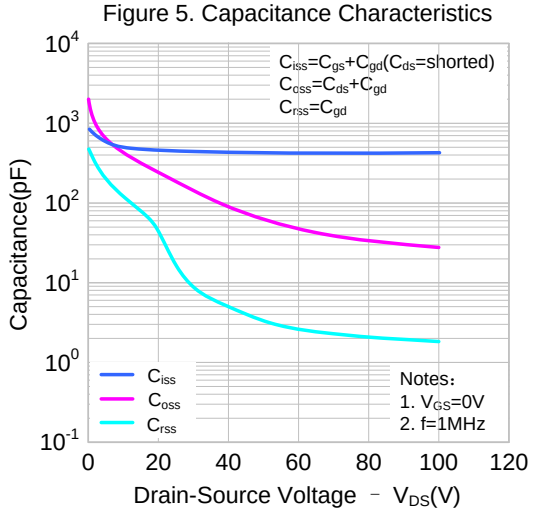
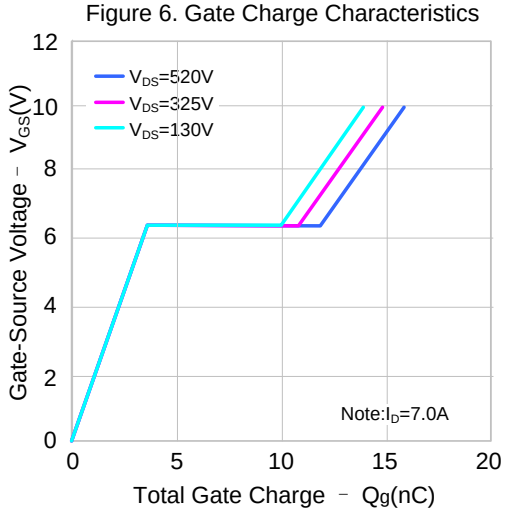


Figure 6. Gate Charge Characteristics



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

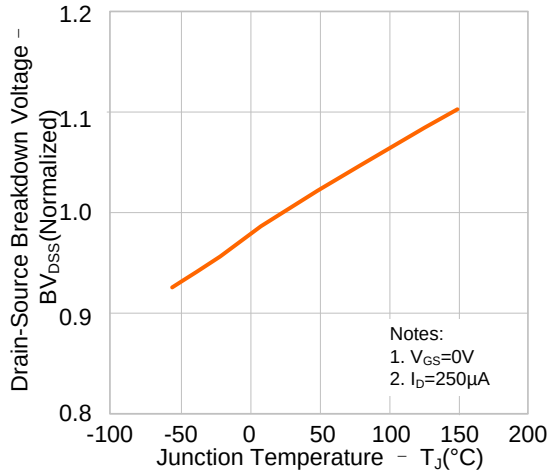


Figure 8. On-resistance Variation vs. Temperature

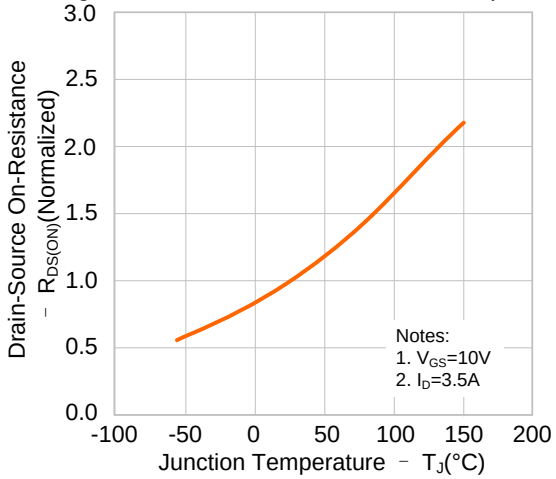


Figure 9-1. Max. Safe Operating Area (SVS7N65DD2/MJD2)

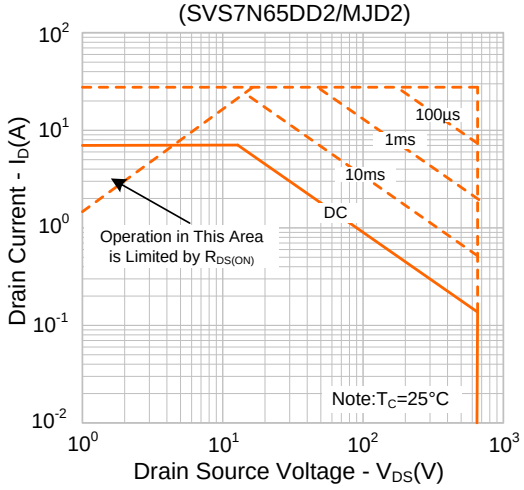
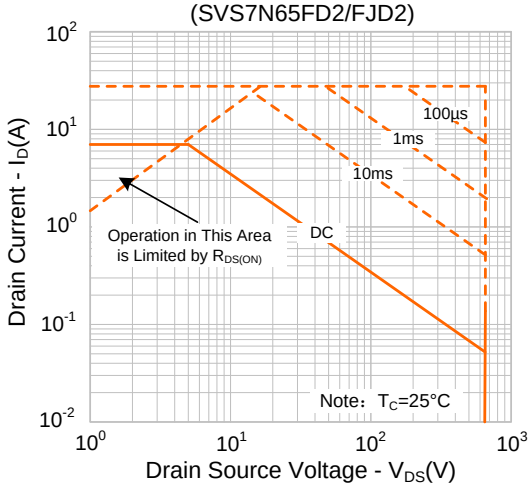
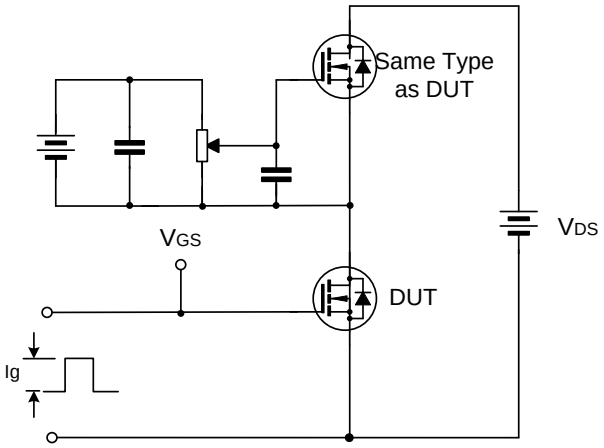


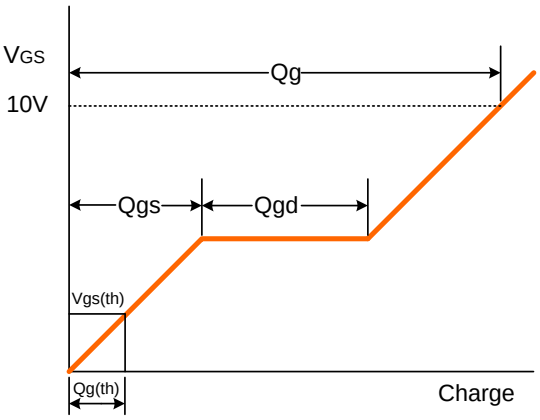
Figure 9-2. Max.Safe Operating Area (SVS7N65FD2/FJD2)



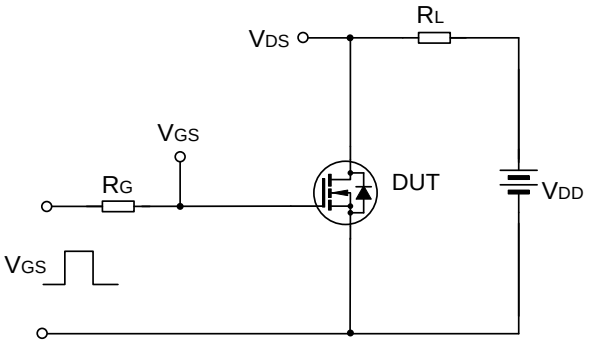
TYPICAL TEST CIRCUIT

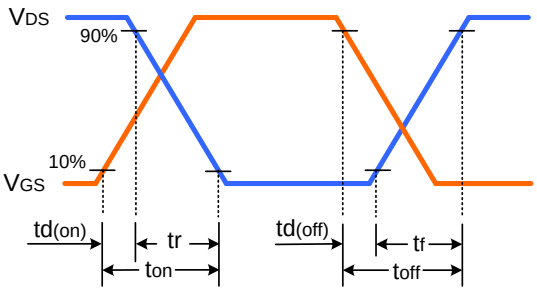
Gate Charge Test Circuit & Waveform



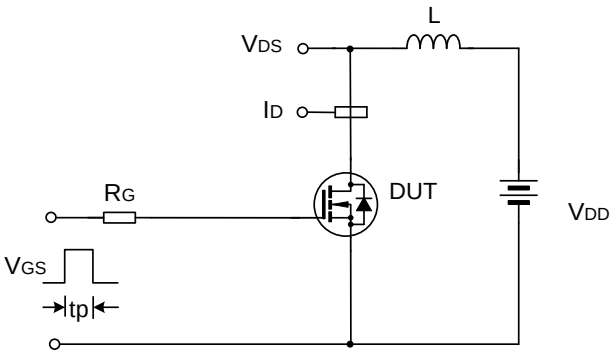


Resistive Switching Test Circuit & Waveform

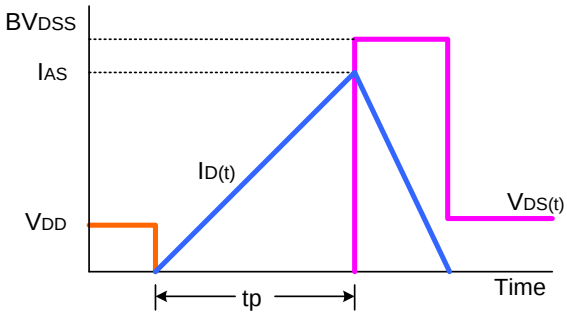




Unclamped Inductive Switching Test Circuit & Waveform



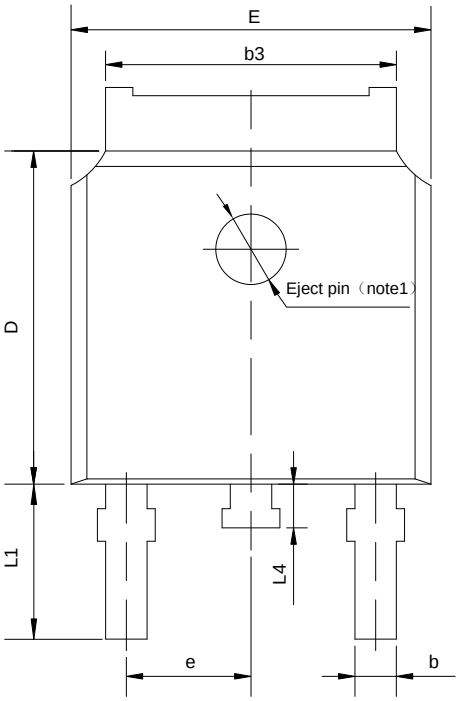
$$E_{AS} = \frac{1}{2} L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

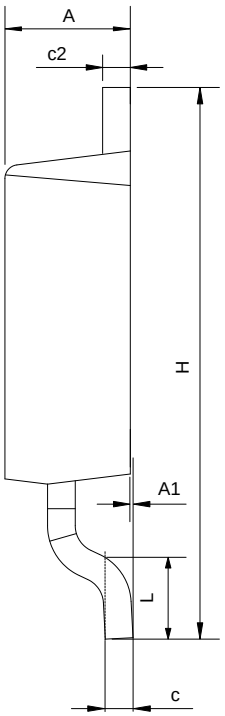


PACKAGE OUTLINE

TO-252-2L

UNIT: mm

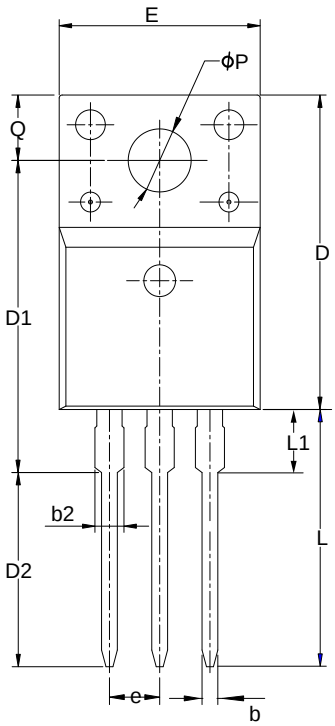


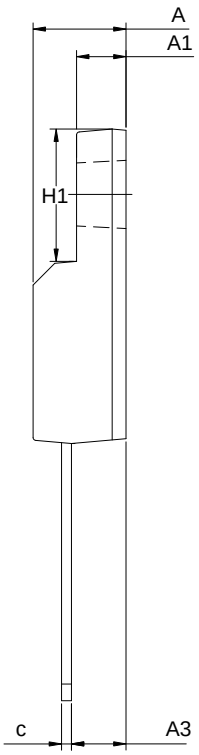


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	—	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	—	0.65
c2	0.45	—	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

TO-220F-3L

UNIT: mm

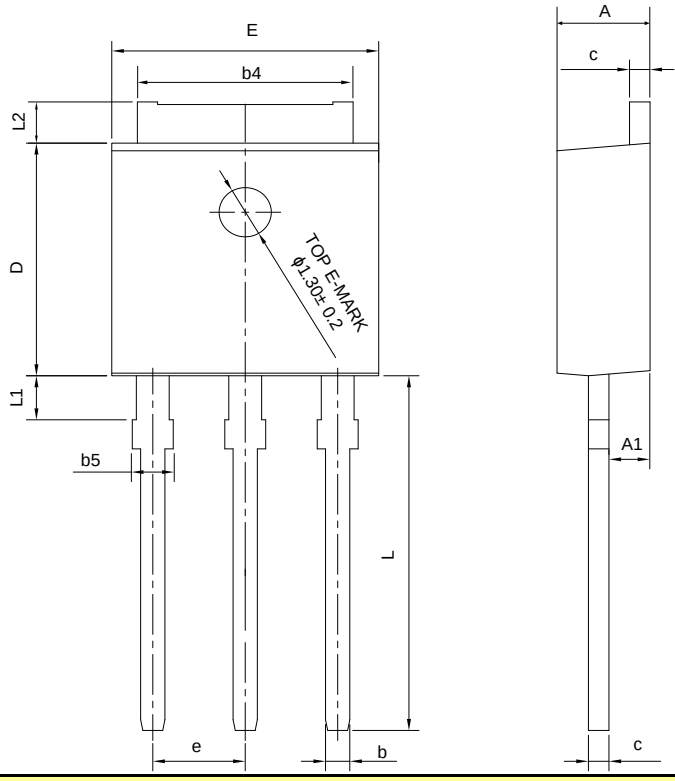




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	–	–	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	–	–	3.50
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

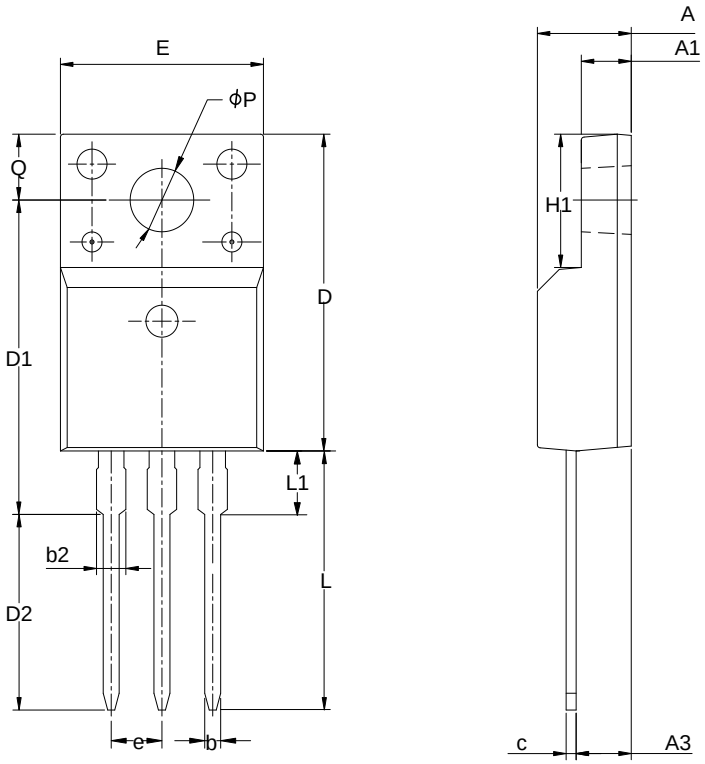
PACKAGE OUTLINE(CONTINUED)

TO-251J-3L **UNIT: mm**



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.18	2.30	2.39
A1	0.89	1.00	1.14
b	0.56	—	0.89
b4	4.95	5.33	5.46
b5	—	—	1.05
c	0.46	—	0.61
D	5.97	6.10	6.27
E	6.35	6.60	6.73
e	2.29 BCS		
L	8.89	9.30	9.65
L1	0.95	—	1.50
L2	0.89	—	1.27

TO-220FJ-3L **UNIT: mm**



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.55	0.70	0.85
b2	—	—	1.29
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	13.97	14.47	14.97
D2	10.58	11.08	11.58
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	2.00
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

Important notice :

- **The instructions are subject to change without notice！ Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.**
- **Our products are consumer electronic products, and / or civil electronic products.**
- **When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.**
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Rev.: 1.6

Revision History:

1. Update Electrical schematic and Typical Test circuit
2. Add R_G
3. Update the template of the datasheet

Rev.: 1.5

Revision History:

1. Modify THERMAL CHARACTERISTICS
2. Add dv/dt of ABSOLUTE MAXIMUM RATINGS

Rev.: 1.4

Revision History:

1. Add the package outline of TO-220FJ-3L
2. Modify Electrical characteristics
3. Modify Ordering information

Rev.: 1.3

Revision History:

1. Add the package outline of TO-251J-3L

Rev.: 1.2

Revision History:

1. Modify characteristics of value Q
2. Update Fig 5 and 6

Rev.: 1.1

Revision History:

1. Add package outline of TO-220F-3L
2. Add Figure9-2

Rev.: 1.0

Revision History:

1. First release